National Semiconductor
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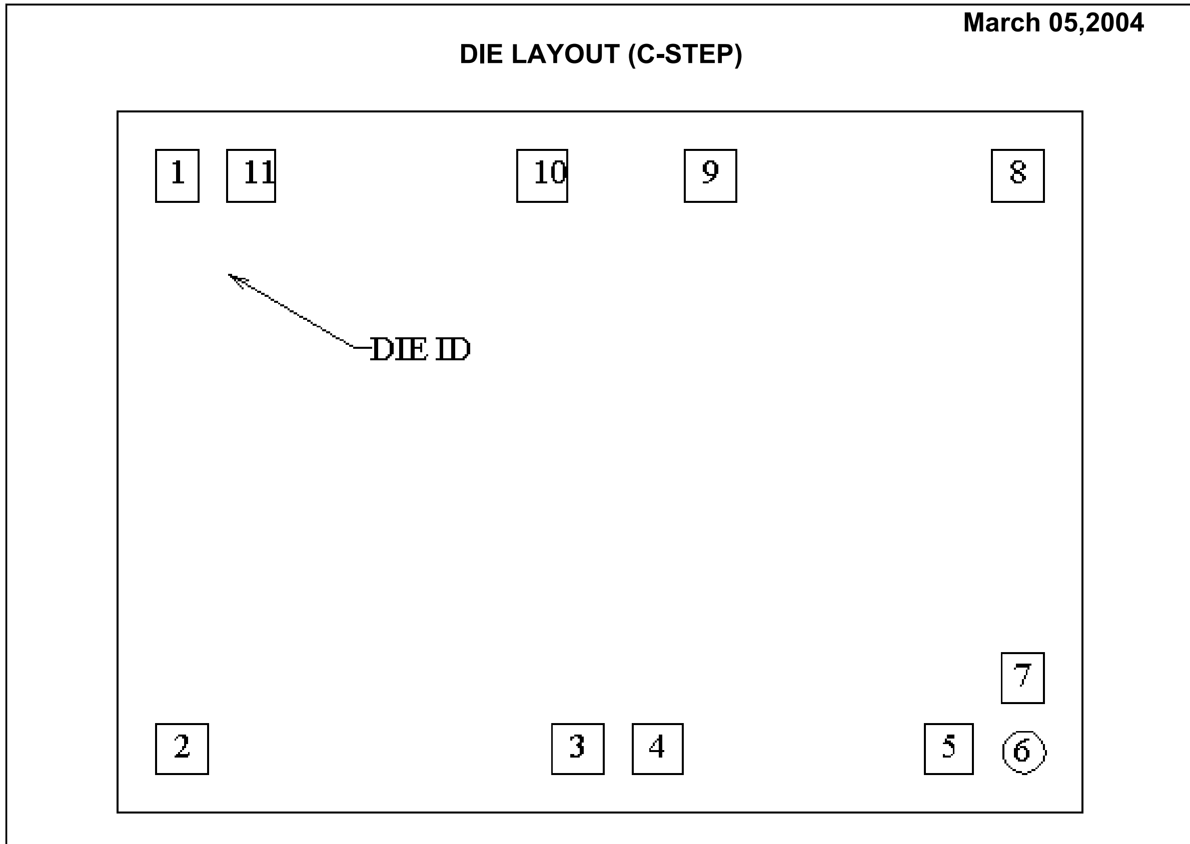
DPBU
Die Datasheet

LM119 MD8 MW8
HIGH SPEED DUAL COMPARATOR

March 05,2004

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	119C	Bond Pad Opening Size (min)	91µm x 109µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Bare Back
Die Size (Drawn)	2057µm x 1499µm 81.0mils x 59.0mils	Back Side Connection	V-
Thickness	330µm Nominal		
Min Pitch	157µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron. V- connected to die backside.

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Die Bond Pad Coordinate Locations (C -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Output 1	1	-902	613	91	x	109
GND 1	2	-893	-613	109	x	109
+Input 1	3	-47	-613	109	x	109
-Input 1	4	123	-613	109	x	109
V-	5	744	-613	102	x	109
NC	6	902	-622	91	x	91
Output 2	7	902	-461	91	x	109
Gnd 2	8	893	613	109	x	109
+Input 2	9	237	613	109	x	109
-Input 2	10	-123	613	109	x	109
V+	11	-744	613	102	x	109

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